

2019 IEEE

International Conference on
Robotics and Automation

May 20-24, 2019 Montreal, Canada



Call for contributions:

IEEE ICRA19 conference INDUSTRY FORUM

<https://icra2019.org/>, www.ras-industryforum.org

Opportunity for increased participation from industrial representatives and scientific programs targeting industrial attendees at ICRA19 Industry Forum, May 20, 2019, Montreal

We ask you to submit your work to gain better visibility to potentially high-impact, innovative research and development projects that demonstrate substantial engineering quality, but may not qualify for acceptance based solely on their scientific novelty due to the research-centric nature of typical ICRA sessions. This Industry Forum publication can expand your work's influence and prominence in the robotics field. This session within the Industry Forum is an opportunity to share translational research best practices.

Form of contribution: 2-4 page extended abstracts (IEEE standard double-column format) submitted to haidegger@ieee.org in pdf.

Submission deadline: no later than May 18, 2019.

Evaluation: Submissions undergo peer review by a panel selected by IEEE RAS IAB. Feedback to authors is provided immediately.

Presentation: upon acceptance, authors may choose between a 10 min oral or poster with 1 min teaser talk format. Presentations should have interactive parts, demonstrations, video, etc to attract/entertain a wider audience.

Publication: accepted works will be published online, in a Forum proceedings, while selected works will be invited to get extended to a full article for submission to a Special Issue on Translational Research in Acta Polytechnica (IF: 0.9, OA at no charge) in Q4.

Presentation schedule: at the ICRA Industry Forum, May 20, 2019 Monday (10:45-17:30) according to www.ras-industryforum.org

This year is considered to be a pilot towards establishing a standing translational research track at ICRA. Please contribute!

Share the call with your colleagues!

Questions/info: Tamas Haidegger, haidegger@ieee.org